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Shuo Huang

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Education

2014-present	University of Michigan Ph.D., Electrical Engineering <i>Advisor: Mark J. Kushner</i>	Ann Arbor, MI
2011-2014	Shanghai Jiao Tong University M.S., Electronics Science and Technology <i>Advisor: Jon Tomas Gudmundsson</i>	Shanghai, China
2007-2011	Southeast University B.E., Electrical Engineering and Its Automation	Nanjing, China

Research Projects

6/2016-present	Feature scale modeling of plasma etching of high aspect ratio contacts in SiO ₂ – <i>Sponsored by Samsung Electronics</i> <ul style="list-style-type: none">• Developed surface reaction mechanism for plasma etching of SiO₂ by Ar/C₄F₈/O₂ mixtures• Investigated aspect ratio dependent etching, bowing and contact edge roughness in the etching of SiO₂ using 3-dimensional Monte Carlo Feature Profile Model (MCFPM)
12/2016-3/2018	Accelerated computation for efficient scientific simulation – <i>Sponsored by DARPA</i> <ul style="list-style-type: none">• Implemented memristor-based PDE solver into the subroutine for solving the Poisson's equation in 2-dimensional Hybrid Plasma Equipment Model (HPEM)• Evaluation of memristor-based PDE solver by modeling an inductively coupled plasma reactor using HPEM and making comparison with high-precision digital solver
8/2014-12/2017	Reactor scale modeling of selective etching of Si ₃ N ₄ by remote plasma source – <i>Sponsored by Samsung Electronics</i> <ul style="list-style-type: none">• Developed reaction mechanism of Ar/NF₃/O₂/HBr and Ar/NF₃/O₂/HCl for selective etching of Si₃N₄ over SiO₂• Investigated reaction pathway and optimization of radical generation by multiple remote sources and multiple gas inlets using volume averaged global model (Global_Kin) and HPEM.
9/2011-6/2014	Reactor scale modeling of dual frequency capacitively coupled plasmas <ul style="list-style-type: none">• Developed Cl₂ reaction chemistry for 1-dimensional particle-in-cell object oriented plasma device (oopd1)• Investigated ion energy and angular distributions and the effect of high and low frequencies on plasma properties

Refereed Journal Publications

1. **S. Huang**, V. Volynets, J. R. Hamilton, S. K. Nam, I.-C. Song, S. Lu, J. Tennyson and M. J. Kushner, Downstream etching of silicon nitride using continuous-wave and pulsed remote plasma sources sustained in Ar/NF₃/O₂ mixtures, *Journal of Vacuum Science and Technology A*, **36**, 021305 (2018). [Selected as Editor's Pick]
2. M. A. Zidan, Y. Jeong, J. Lee, B. Chen, **S. Huang**, M. J. Kushner and W. D. Lu, A general memristor-based partial differential equation solver, *Nature Electronics*, **1**, 411 (2018).
3. **S. Huang**, V. Volynets, J. R. Hamilton, S. Lee, I.-C. Song, S. Lu, J. Tennyson and M. J. Kushner, Insights to scaling remote plasma sources sustained in NF₃ mixtures, *Journal of Vacuum Science and Technology A*, **35**, 031302 (2017).
4. J. R. Hamilton, J. Tennyson, **S. Huang** and M. J. Kushner, Calculated cross sections for electron collisions with NF₃, NF₂ and NF with applications to remote plasma sources, *Plasma Sources Science and Technology*, **26**, 065010 (2017).
5. **S. Huang** and J. T. Gudmundsson, Dual frequency capacitively coupled chlorine discharge, *Plasma Sources Science and Technology*, **24**, 015003 (2015).
6. **S. Huang** and J. T. Gudmundsson, Ion energy and angular distributions in a dual-frequency capacitively coupled chlorine discharge, *IEEE Transactions on Plasma Science*, **42**, 2854 (2014).
7. **S. Huang** and J. T. Gudmundsson, A current driven capacitively coupled chlorine discharge, *Plasma Sources Science and Technology*, **23**, 025015 (2014).
8. **S. Huang** and J. T. Gudmundsson, A particle-in-cell/Monte Carlo simulation of a capacitively coupled chlorine discharge, *Plasma Sources Science and Technology*, **22**, 055020 (2013).

Conference Proceedings

1. **S. Huang**, J. R. Hamilton, J. Tennyson and M. J. Kushner, Remote plasma sources sustained in NF₃ mixtures, 22nd *International Symposium on Plasma Chemistry*, Antwerp, Belgium, July 2015.
2. J. R. Hamilton, **S. Huang**, M. J. Kushner and J. Tennyson, Electron NF_x cross sections using UK R-matrix method for use in plasma models, 22nd *International Symposium on Plasma Chemistry*, Antwerp, Belgium, July 2015.

Conference Presentations - Talks

1. **S. Huang**, M. J. Kushner, S. Shim and S. K. Nam, Optimizing uniformity in plasma etching of high aspect ratio features by engineering the focus ring, 45th *IEEE International Conference on Plasma Science*, Denver, Colorado, USA, June 2018.
2. **S. Huang**, C. Huard, P. Tian, C. Qu, S. Lanham, G. Parsey, S. Mohades and M. J. Kushner, High and moderate aspect ratio etching: insights from modeling, 39th *International Symposium on Dry Process*, Tokyo, Japan, November 2017.
3. C. Qu, P. Tian, **S. Huang** and M. J. Kushner, Customizing capacitively coupled plasma properties with triple-frequency power sources, 70th *Gaseous Electronics Conference*, Pittsburgh, Pennsylvania, USA, November 2017.
4. K. Ford, J. Brandon, K. S. Kim, T. List, T. Ma, P. Arora, **S. Huang**, S. K. Nam, S. Shannon, V. Donnelly, M. J. Kushner, Fundamental studies of pulsed processing plasmas, 70th *Gaseous Electronics Conference*, Pittsburgh, Pennsylvania, USA, November 2017.

5. **S. Huang**, V. Volynets, S. Lee, S. K. Nam and S. Lu and M. J. Kushner, Selective radical production in remote plasma sources, *64th International Symposium of the American Vacuum Society*, Tampa, Florida, USA, October 2017.
6. M. J. Kushner, C. Huard, S. Lanham, **S. Huang** and P. Tian, Translating fundamental science to technology development in plasma assisted materials processing: contributions by Harold Winters and their impact on modeling, *64th International Symposium of the American Vacuum Society*, Tampa, Florida, USA, October 2017.
7. **S. Huang**, C. Huard, M. J. Kushner, S. Shim, S-H. Lee, I-C. Song and S. Lu, Contact edge roughness in the etching of high aspect ratio contacts in SiO₂, *44th International Conference on Plasma Science*, Atlantic City, New Jersey, USA, May 2017.
8. **S. Huang**, C. Huard, S. Shim, S. Lee, I-C. Song, S. Lu and M. J. Kushner, Plasma etching of high aspect ratio contacts in SiO₂ using Ar/C₄F₈/O₂ mixtures: a computational investigation, *63rd International Symposium of the American Vacuum Society*, Nashville, Tennessee, USA, November 2016.
9. P. Tian, **S. Huang**, S. Shim, S. Lee, I-C. Song, S. Lu and M. J. Kushner, Control of uniformity and ion energy distributions in tri-frequency capacitively coupled plasmas accounting for finite wavelength effects, *63rd International Symposium of the American Vacuum Society*, Nashville, Tennessee, USA, November 2016.
10. J. R. Hamilton, **S. Huang**, M. J. Kushner, S. Rahimi, C. Hill, A. Dzarasova and J. Tennyson, Quantemol validated chemistry database: calculated cross sections for electron NF_x collisions as an example, *10th International Conference on Atomic and Molecular Data and Their Applications*, Gunsan, Republic of Korea, September 2016.
11. **S. Huang**, V. Volynets, S. Lee, I-C. Song, S. Lu, J. R. Hamilton, J. Tennyson and M. J. Kushner, Optimizing remote plasma sources for selective etching, *43rd IEEE International Conference on Plasma Science*, Banff, Canada, June 2016.
12. **S. Huang**, V. Volynets, S. Lee, I-C. Song, S. Lu, J. R. Hamilton, J. Tennyson and M. J. Kushner, Insights to scaling remote plasma sources sustained in NF₃ mixtures, *62nd International Symposium of the American Vacuum Society*, San Jose, California, USA, October 2015.
13. **S. Huang**, V. Volynets, S. Lee, I-C. Song, S. Lu, J. R. Hamilton, J. Tennyson and M. J. Kushner, Dry etching of Si₃N₄ using remote plasma sources sustained in NF₃ mixtures, *68th Gaseous Electronics Conference*, Honolulu, Hawaii, USA, October 2015.
14. **S. Huang**, J. R. Hamilton, J. Tennyson and M. J. Kushner, Remote plasma sources sustained in NF₃ mixtures, *22nd International Symposium on Plasma Chemistry*, Antwerp, Belgium, July 2015.
15. **S. Huang** and J. T. Gudmundsson, Dual frequency capacitively coupled chlorine discharge, *Gordon Research Seminar on Plasma Processing Science*, Smithfield, Rhode Island, USA, July 2014.
16. J. T. Gudmundsson and **S. Huang**, A particle-in-cell/Monte Carlo simulation of a capacitively coupled chlorine discharge, *66th Gaseous Electronics Conference*, Princeton, New Jersey, USA, October 2013.

Conference Presentations - Posters

1. **S. Huang** and M. J. Kushner, Optimizing uniformity in plasma etching of high aspect ratio features by engineering the focus ring, *Gordon Research Conference on Plasma Processing Science*, Smithfield, Rhode Island, USA, August 2018.

2. **S. Huang** and M. J. Kushner, Multiple remote plasma sources for selective etching, *Gordon Research Conference on Plasma Processing Science*, Andover, New Hampshire, USA, July 2016.
3. J. R. Hamilton, **S. Huang**, M. J. Kushner and J. Tennyson, Electron NF_x cross sections using UK R-matrix method for use in plasma models, *22nd International Symposium on Plasma Chemistry*, Antwerp, Belgium, July 2015.
4. **S. Huang** and J. T. Gudmundsson, Particle-in-cell/Monte Carlo simulation of dual frequency capacitively coupled chlorine discharge, *67th Gaseous Electronics Conference*, Raleigh, North Carolina, USA, November 2014.
5. J. T. Gudmundsson and **S. Huang**, Current driven dual-frequency capacitively coupled discharge in chlorine, *The XXII Europhysics Conference on Atomic and Molecular Physics of Ionized Gases*, Greifswald, Germany, July 2014.

Theses

- M.S. Thesis Particle-in-cell/Monte Carlo simulation of single and dual frequency capacitively coupled chlorine discharges, Shanghai Jiao Tong University, Shanghai, China, March 2014.
 Advisor: Jon Tomas Gudmundsson
 Committee: Jon Tomas Gudmundsson, Yaping Dan and Hua Bao
- B.E. Thesis Particle swarm optimization applied in state estimation for IEEE 36-bus network, Southeast University, Nanjing, China, June 2011.
 Advisor: Qingshan Xu